

## 1. General description

AC Thyristor Triac power switch in a DPAK surface mountable plastic package with self-protective clamping capabilities against low and high energy transients. This "series CTN" triac will commutate the full RMS current at the maximum rated junction temperature ( $T_{j(max)} = 150\text{ °C}$ ) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

## 2. Features and benefits

- Clamping structure ensuring safe high over-voltage withstand capability
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ °C}$ )
- High minimum  $I_{GT}$  for guaranteed immunity to gate noise
- Full cycle AC conduction
- Over-voltage withstand capability to IEC 61000-4-5
- Pin compatible with standard triacs
- Planar passivated for voltage ruggedness and reliability
- Protective self turn-on capability for high energy transients
- Safe clamping capability for low energy over-voltage transients
- Less sensitive gate for high noise immunity
- Surface mountable package
- Triggering in three quadrants only
- Very high immunity to false turn-on by  $dV/dt$  and IEC 61000-4-4 fast transient
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant

## 3. Applications

- AC fan, pump and compressor controls
- Highly inductive, resistive and safety loads
- Large and small appliances (White Goods)
- Reversing induction motor controls
- Applications subject to high temperature ( $T_{j(max)} = 150\text{ °C}$ )

## 4. Quick reference data

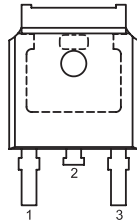
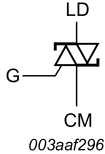
Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage			800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 134\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		12	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		120	A
		full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$		132	A
$T_j$	junction temperature			-40 to 150	°C
$V_{PP}$	peak pulse voltage	$T_j = 25\text{ °C}$ ; non-repetitive off-state; <a href="#">Fig. 6</a>		2	kV

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 100 mA; LD+ G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 100 mA; LD+ G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 100 mA; LD- G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		5	-	35	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>J</sub> = 25 °C; <a href="#">Fig. 10</a>		-	-	30	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 17 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 11</a>		-	-	1.5	V
V <sub>CL</sub>	clamping voltage	I <sub>CL</sub> = 0.1 mA; t <sub>p</sub> = 1 ms; T <sub>J</sub> = 25 °C		850	-	-	V
<b>Dynamic characteristics</b>							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>J</sub> = 150 °C; exponential waveform; gate open circuit		2000	-	-	V/μs
dI <sub>com</sub> /dt	rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>J</sub> = 150 °C; I <sub>T(RMS)</sub> = 12 A; dV <sub>com</sub> /dt = 20 V/μs; gate open circuit; snubberless condition		12	-	-	A/ms

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	CM	common		
2	LD	load		
3	G	gate		
mb	LD	mounting base; load		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
ACTT12S-800CTN	TO252	ACTT12S-800CTNJ	Reel	2500	TO252N	14-Nov-2016

## 7. Marking

Table 4. Marking codes

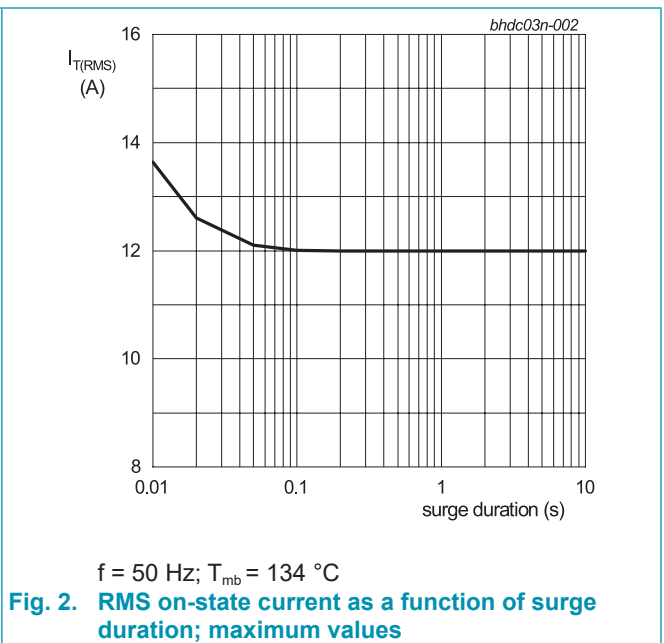
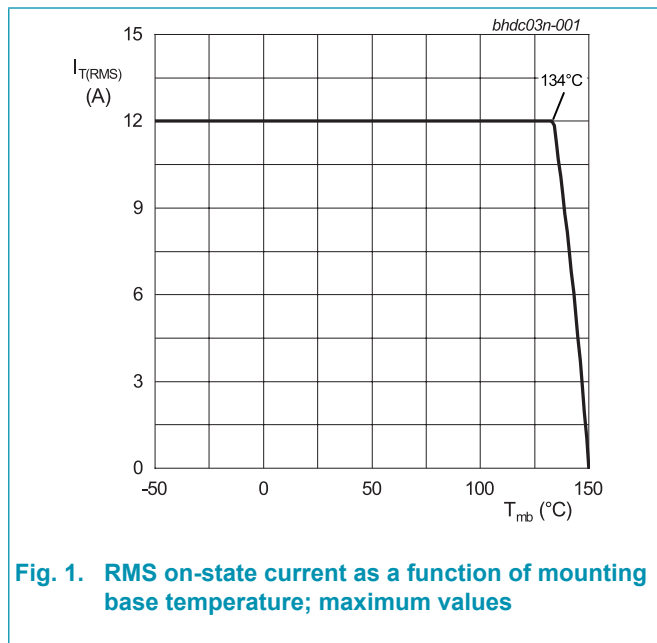
Type number	Marking codes
ACTT12S-800CTN	ACTT12S 800CTN

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage			800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 134\text{ °C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		12	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig 4</a> ; <a href="#">Fig 5</a>		120	A
		full sine wave; $T_{j(init)} = 25\text{ °C}$ ; $t_p = 16.7\text{ ms}$		132	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse		72	$A^2s$
$di_T/dt$	rate of rise of on-state current	$I_G = 70\text{ mA}$		100	$A/\mu s$
$I_{GM}$	peak gate current	$t_p = 20\text{ }\mu s$		2	A
$P_{GM}$	peak gate power			5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
$T_{stg}$	storage temperature			-40 to 150	$^{\circ}C$
$T_j$	junction temperature			-40 to 150	$^{\circ}C$
$V_{pp}$	peak pulse voltage	$T_j = 25\text{ °C}$ ; non-repetitive, off-state; <a href="#">Fig 6</a>		2	kV



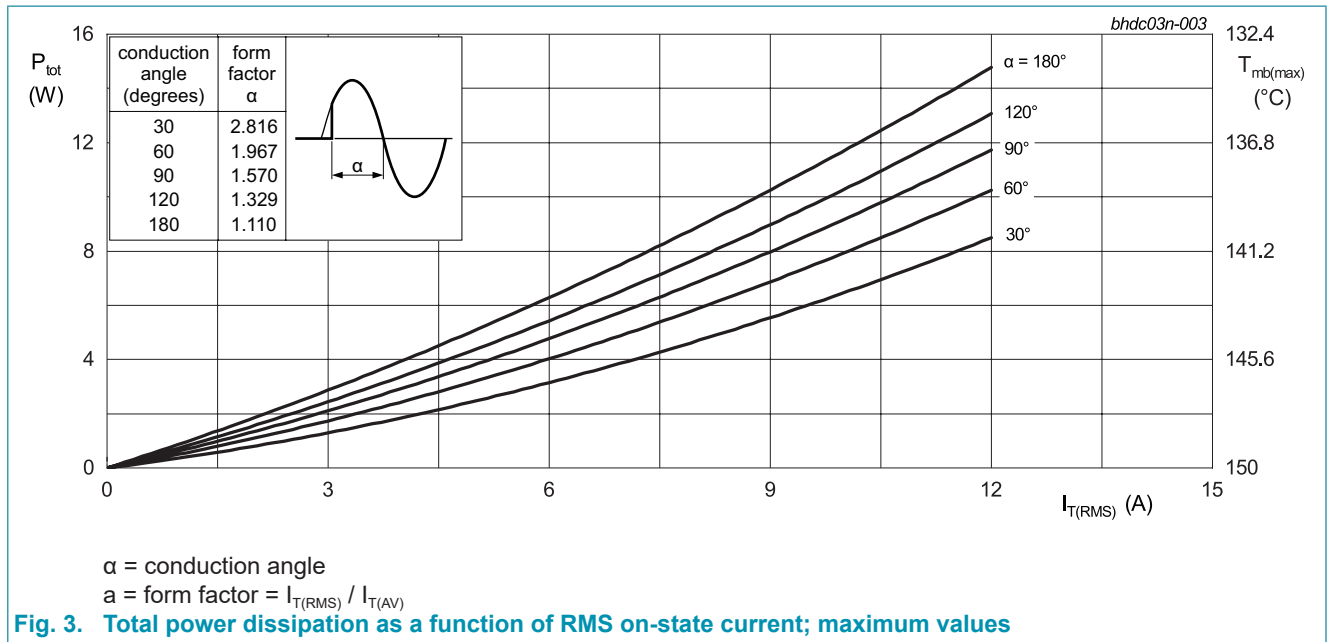


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

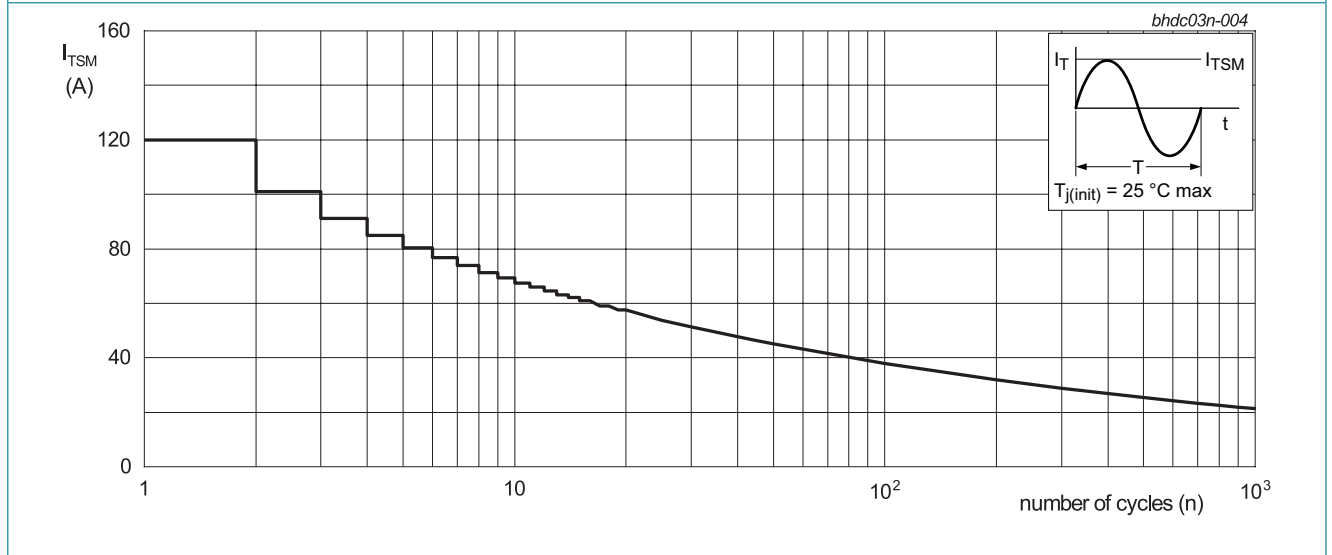
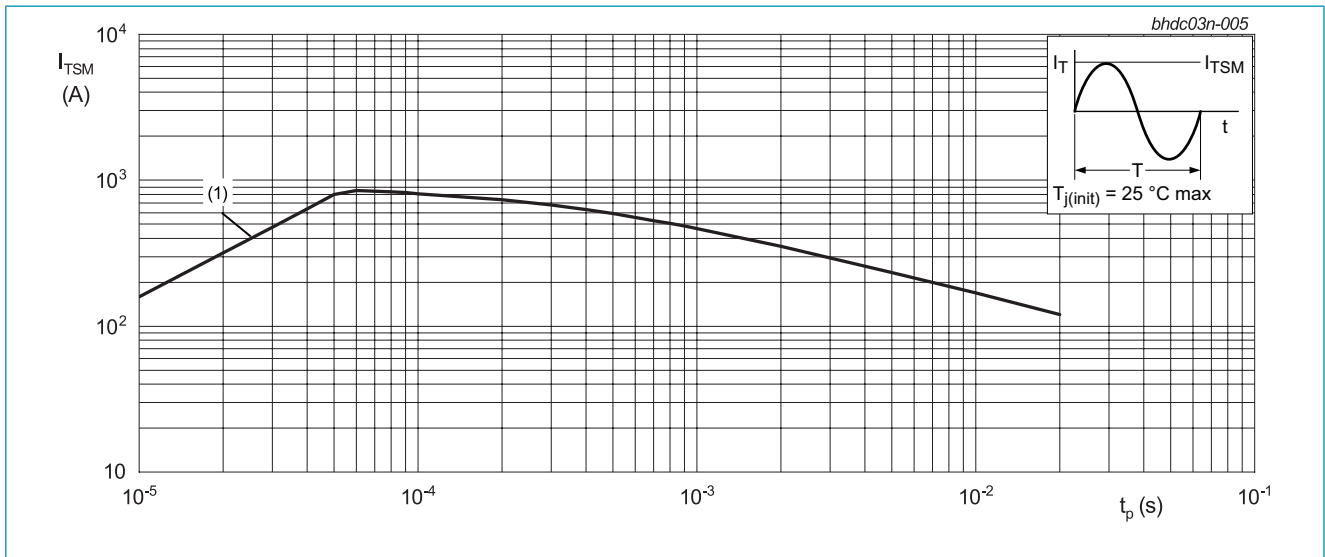


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20 \text{ ms}$   
 (1)  $di_T/dt$  limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

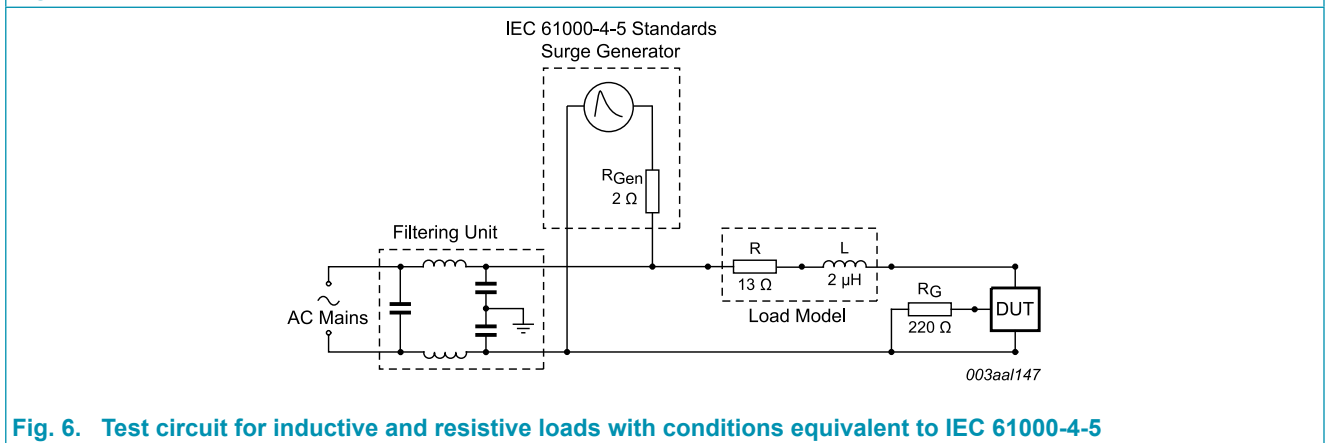


Fig. 6. Test circuit for inductive and resistive loads with conditions equivalent to IEC 61000-4-5

## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; <a href="#">Fig. 7</a>		-	-	1.1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; printed circuit board (FR4) mounted		-	70	-	K/W

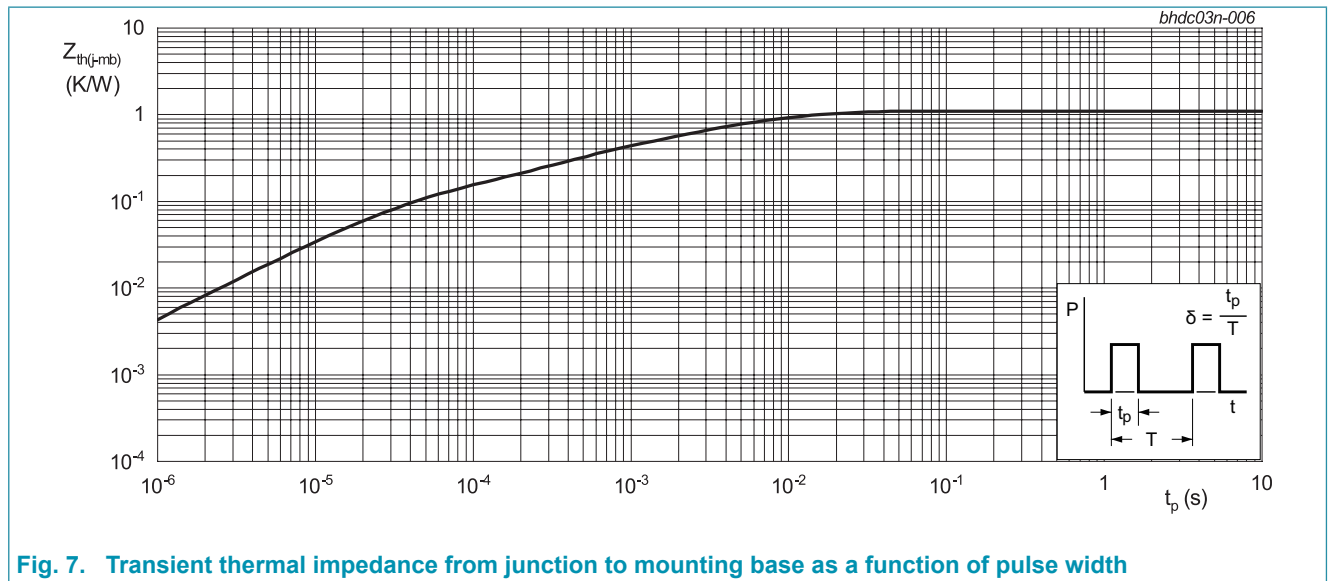
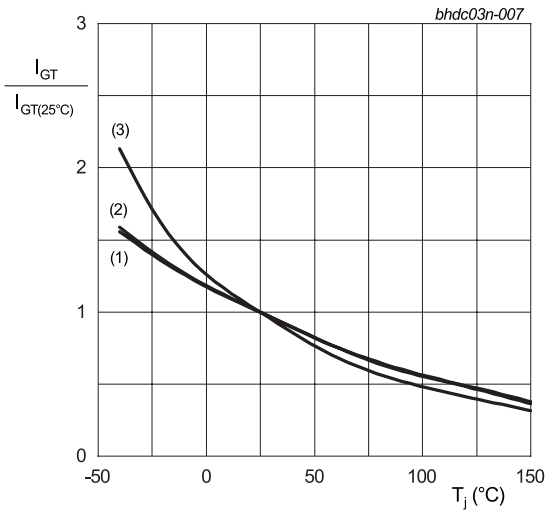


Fig. 7. Transient thermal impedance from junction to mounting base as a function of pulse width

## 10. Characteristics

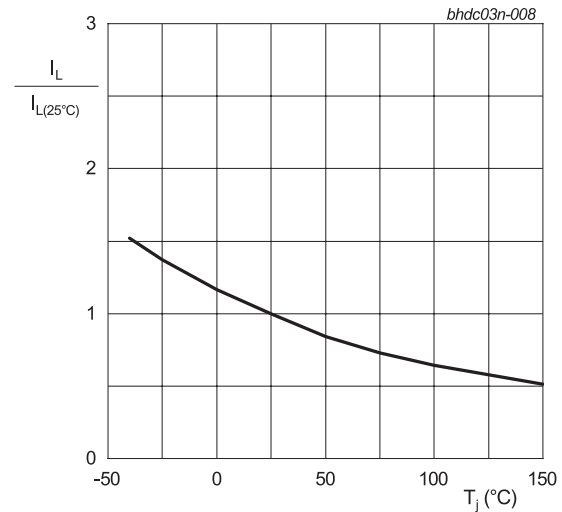
Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 100\text{ mA}$ ; LD+ G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 8</a>		5	-	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 100\text{ mA}$ ; LD+ G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 8</a>		5	-	35	mA
		$V_D = 12\text{ V}$ ; $I_T = 100\text{ mA}$ ; LD- G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 8</a>		5	-	35	mA
$I_L$	latching current	$V_D = 12\text{ V}$ ; $I_G = 100\text{ mA}$ ; LD+ G+; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>		-	-	40	mA
		$V_D = 12\text{ V}$ ; $I_G = 100\text{ mA}$ ; LD+ G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>		-	-	60	mA
		$V_D = 12\text{ V}$ ; $I_G = 100\text{ mA}$ ; LD- G-; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 9</a>		-	-	40	mA
$I_H$	holding current	$V_D = 12\text{ V}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 10</a>		-	-	30	mA
$V_T$	on-state voltage	$I_T = 17\text{ A}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 11</a>		-	-	1.5	V
$V_{GT}$	gate trigger voltage	$V_D = 12\text{ V}$ ; $I_T = 100\text{ mA}$ ; $T_j = 25\text{ °C}$ ; <a href="#">Fig. 12</a>		-	0.75	1	V
		$V_D = 400\text{ V}$ ; $I_T = 100\text{ mA}$ ; $T_j = 150\text{ °C}$		0.2	0.45	-	V
$I_D$	off-state current	$V_D = 800\text{ V}$ ; $T_j = 25\text{ °C}$		-	-	1	$\mu\text{A}$
		$V_D = 800\text{ V}$ ; $T_j = 150\text{ °C}$		-	-	1	mA
$I_R$	reverse current	$V_R = 800\text{ V}$ ; $T_j = 25\text{ °C}$		-	-	1	$\mu\text{A}$
		$V_R = 800\text{ V}$ ; $T_j = 150\text{ °C}$		-	-	1	mA
$V_{CL}$	clamping voltage	$I_{CL} = 0.1\text{ mA}$ ; $t_p = 1\text{ ms}$ ; $T_j = 25\text{ °C}$		850	-	-	V
<b>Dynamic characteristics</b>							
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$ ; $T_j = 150\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit		2000	-	-	V/ $\mu\text{s}$
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400\text{ V}$ ; $T_j = 150\text{ °C}$ ; $I_{T(RMS)} = 12\text{ A}$ ; $dV_{com}/dt = 20\text{ V}/\mu\text{s}$ ; gate open circuit; snubberless condition		12	-	-	A/ms

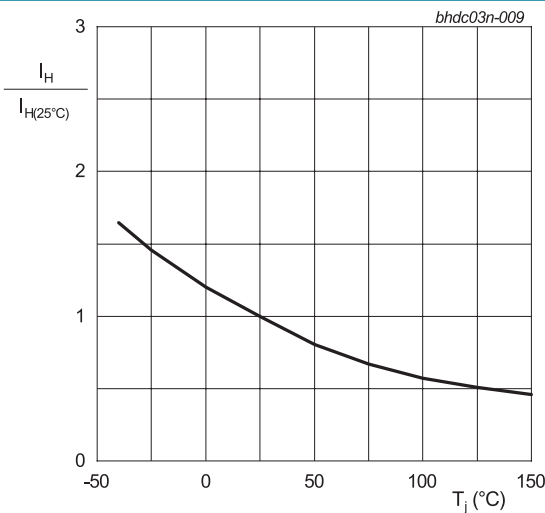


- (1) LD+ G-
- (2) LD+ G+
- (3) LD- G-

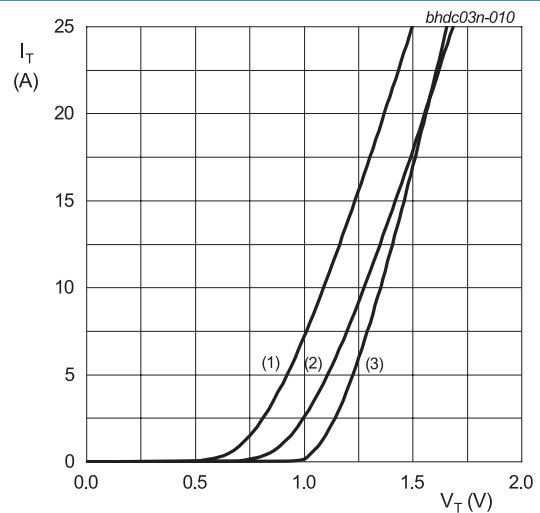
**Fig. 8. Normalized gate trigger current as a function of junction temperature**



**Fig. 9. Normalized latching current as a function of junction temperature**



**Fig. 10. Normalized holding current as a function of junction temperature**



- $V_o = 0.959 \text{ V}; R_s = 0.0306 \text{ } \Omega$
- (1)  $T_j = 150 \text{ } ^\circ\text{C}$ ; typical values
  - (2)  $T_j = 150 \text{ } ^\circ\text{C}$ ; maximum values
  - (3)  $T_j = 25 \text{ } ^\circ\text{C}$ ; maximum values

**Fig. 11. On-state current as a function of on-state voltage**



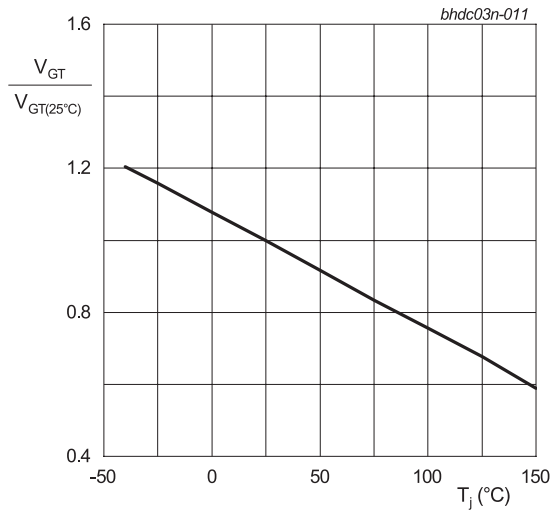
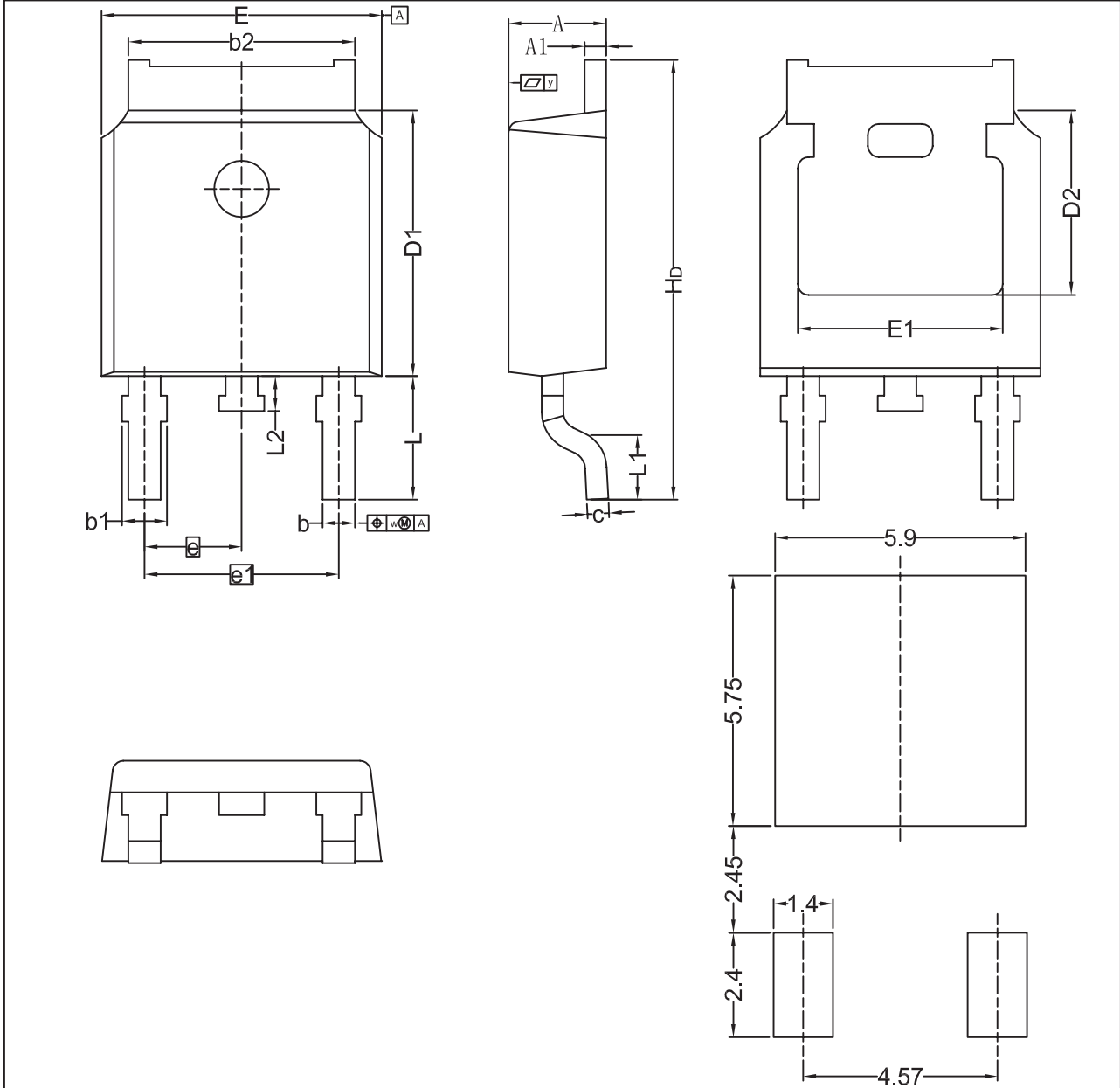


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

### 11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

TO252



Recommended Footprint

Unit	A	A1	b	b1	b2	c	D1	D2	E	E1	e	e1	H <sub>D</sub>	L	L1	L2	w	y
min	2.22	0.46	0.71	0.72	5.00	0.20	5.98	4.00	6.47	4.45			9.60	2.90	0.50	0.50		
mm nom											2.285	4.57		(Ref.)			0.20	
max	2.38	0.93	0.89	1.10	5.46	0.56	6.22	---	6.73	---			10.40	---	0.90			0.20

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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